

Vishay Siliconix

N-Channel 1.2-V (G-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A)	Q _g (Typ.)		
	0.026 at $V_{GS} = 4.5 \text{ V}$	9 ^a			
	0.030 at V _{GS} = 2.5 V	9 ^a			
8	0.037 at V _{GS} = 1.8 V	9 ^a	8.6 nC		
	0.052 at V _{GS} = 1.5 V	9 ^a			
	0.089 at V _{GS} = 1.2 V	9 ^a			

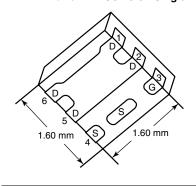
FEATURES

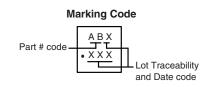
- Halogen-free
- TrenchFET[®] Power MOSFET
- New Thermally Enhanced PowerPAK[®] SC-75 Package
 - Small Footprint Area
 - Low On-Resistance



RoHS

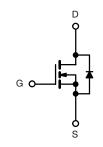
PowerPAK SC-75-6L-Single





APPLICATIONSLoad Switch, PA Switch

- Load Switch, PA Switch and Battery Switch for Portable Devices
- DC/DC Converter



N-Channel MOSFET

	Ordering Information:	: SiB414DK-T1-GE3	(Lead	(Pb)-free	and Haloge	n-free)
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ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise n	oted	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	8	V
Gate-Source Voltage		V_{GS}	± 5]
Continuous Drain Current (T _J = 150 °C)	$T_C = 25 ^{\circ}\text{C}$ $T_C = 70 ^{\circ}\text{C}$ $T_A = 25 ^{\circ}\text{C}$	I _D	9 ^a 9 ^a 7.9 ^{b, c}	A
T _A = 70 °C Pulsed Drain Current		I _{DM}	6.3 ^{b, c} 20	^
Continuous Source-Drain Diode Current	T _C = 25 °C T _A = 25 °C	I _S	9 ^a 2 ^{b, c}	
Maximum Power Dissipation	$T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 70 ^{\circ}\text{C}$ $T_{A} = 25 ^{\circ}\text{C}$ $T_{A} = 70 ^{\circ}\text{C}$	P _D	13 8.4 2.4 ^{b, c} 1.6 ^{b, c}	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) ^{d, e}			260	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}	t ≤ 5 s	R_{thJA}	41	51	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	7.5	9.5		

Notes:

- a. Package limited.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SC-75 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under Steady State conditions is 105 °C/W.

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SPECIFICATIONS T_J = 25 $^{\circ}C$	unless oth	erwise noted					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	8			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		9.42		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$,		- 2.52			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	0.35		1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 5 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 8 \text{ V}, V_{GS} = 0 \text{ V}$			1	μА	
Zero date voltage Diam ourient		$V_{DS} = 8 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 7.9 \text{ A}$		0.021	0.026	1	
		V _{GS} = 2.5 V, I _D = 7. 4 A		0.0246	0.030	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 1.8 \text{ V}, I_D = 6.6 \text{ A}$		0.030	0.037		
		V _{GS} = 1.5 V, I _D = 1.92 A		0.037	0.052		
		V _{GS} = 1.2 V, I _D = 1.02 A		0.059	0.089		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 4 \text{ V}, I_{D} = 7.9 \text{ A}$		27		S	
Dynamic ^b				1			
Input Capacitance	C _{iss}			732		pF	
Output Capacitance	C _{oss}	$V_{DS} = 4 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		280			
Reverse Transfer Capacitance	C _{rss}			195			
		$V_{DS} = 4 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 7.9 \text{ A}$		9.35	14.03		
Total Gate Charge	Q_g			8.6	13	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 4 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 7.9 \text{ A}$		0.53			
Gate-Drain Charge	Q_{gd}			2.78			
Gate Resistance	R_g	f = 1 MHz		3.6		Ω	
Turn-On Delay Time	t _{d(on)}			7	10.5	- ns	
Rise Time	t _r	V_{DD} = 4 V, R_L = 0.64 Ω		13	19.5		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 6.3 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		50	75		
Fall Time	t _f			14	21		
Drain-Source Body Diode Characterist	ics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			9	^	
Pulse Diode Forward Current	I _{SM}				20	Α	
Body Diode Voltage	V_{SD}	$I_S = 3.2 \text{ A}, V_{GS} = 0 \text{ V}$		0.7	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			23	35	ns	
Body Diode Reverse Recovery Charge	Q_{rr}	I _F = 3.2 A, di/dt = 100 A/μs, T _J = 25 °C		8.1	12.15	nC	
Reverse Recovery Fall Time	t _a	$_{1F} = 0.2$ A, $_{1J} = 25$ °C		13.3		20	
Reverse Recovery Rise Time	t _b	7		9.6		ns	

Notes:

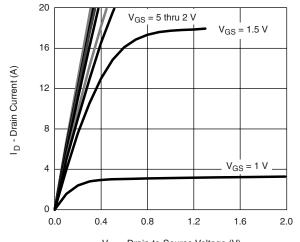
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



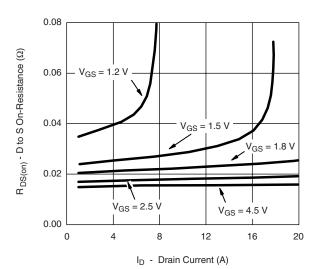
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

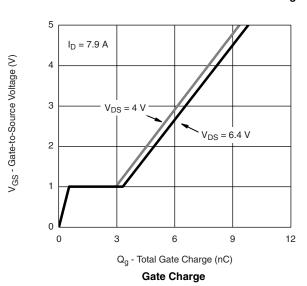


V_{DS} - Drain-to-Source Voltage (V)

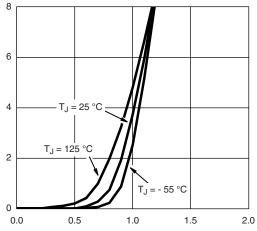




On-Resistance vs. Drain Current and Gate Voltage

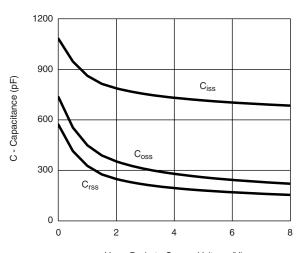






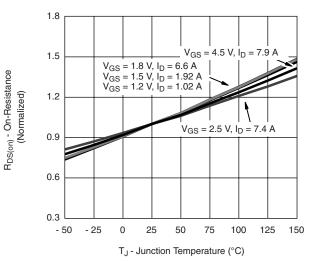
 $V_{\mbox{\footnotesize GS}}$ - Gate-to-Source Voltage (V)





V_{DS} - Drain-to-Source Voltage (V)

Capacitance



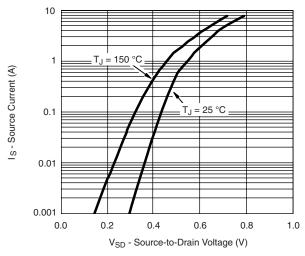
On-Resistance vs. Junction Temperature

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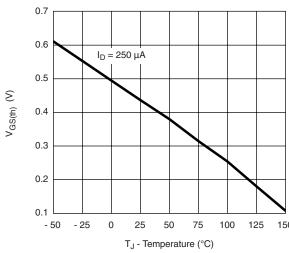
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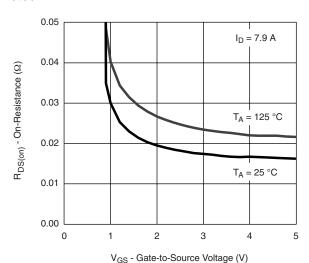
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



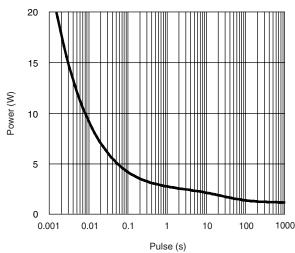
Soure-Drain Diode Forward Voltage



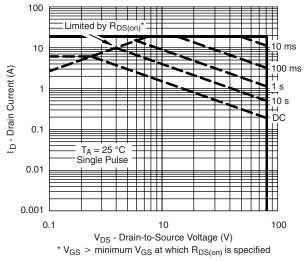
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

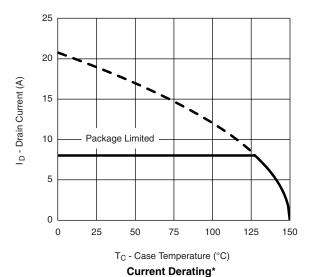


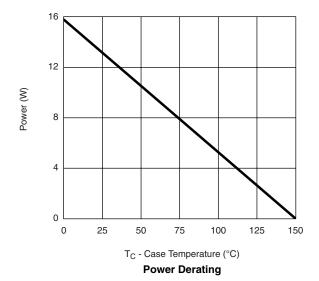
Safe Operating Area, Junction-to-Case



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





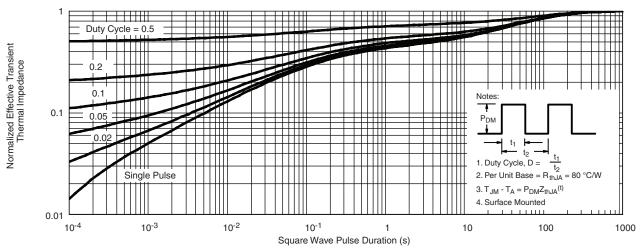
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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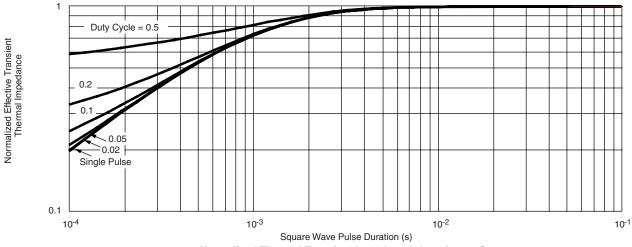
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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